August 2014 eBeam Initiative Survey

Goals:

- Increase the voice of the eBeam community
- Explore key themes and gain insights
- Thank you to the luminaries for their responses (N=52)
 - 52 in 2014
 - 49 in 2013
 - 42 in 2012





Multibeam Mask Sentiment Still Positive: The question is when?



Repeat Q: Do you believe that multibeam technology will be used for mask or wafer writing production by 2016?



Multibeam Mask Volume Production Expectations High Beyond 2016



New Q: When do you believe that multibeam technology will be used for high volume manufacturing mask writing?



Multibeam to Drive Complex ArF-i Masks

New Q: With the emergence of multibeam technology, will the industry take advantage of more complex shapes?

Mask Hotspots Becoming a Reality

Repeat Q: When did you start -- or do you anticipate -- seeing mask hotspots as a significant issue in semiconductor manufacturing?

Dose Modulation is Inevitable

New Q: By 2016, how many levels of dose modulation will be required of the input files to the mask writers?

Slower Resists, Higher Dose

New Q: When will leading-edge production masks use resists slower than 80 µC/cm2?

Several Drivers of Mask 3D Effects Likely

New Q: On what type of masks will it be important to model mask 3D effects (including shape-specific sidewall angles)?

GPU Usage is Expected

Repeat Q: By 2020, what percentage of simulation-intensive applications in EDA will use GPUs?

EUV Pessimism Increases

Repeat Q: In what year do you predict EUV will be used in high volume manufacturing for SoCs?

Strong CEBL Optimism

New Q: When do you believe complementary eBeam lithography (CEBL) will be used in production manufacturing?

2015 Top Four Themes: Multibeam, CEBL, Complex Masks, MB-MDP

New Q: Please select which topics you would like to hear more about from the eBeam Initiative community in 2015.

Thank you to those who participated in the survey!

Feedback and questions for future surveys welcome – send to jan@williscalibra.com

